

Customer No.: 31561
Application No.: 10/604,509
Docket No.: 10380-US-PA

AMENDMENTS TO SPECIFICATION

Please amend the specification as follows:

[0012] An object of this invention is to provide a semiconductor device and manufacturing method thereof having a lower overall thermal budget.

[0013] An object of this invention is to provide a semiconductor device and manufacturing method thereof capable of producing an internal structure with a lower aspect ratio so that the process window for etching out contacts is increased.

[0014] An object of this invention is to provide a semiconductor device and manufacturing method thereof capable of producing a device with optimal short channel properties.